

N-Channel 150 V (D-S) MOSFET

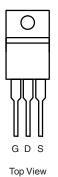
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)		
150	0.0085 at V _{GS} = 10 V	100	60 nC		
	0.0095 at V _{GS} = 7.5 V	98	60 HC		

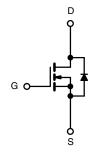
FEATURES

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- 100 % R_q and UIS tested









N-Channel MOSFET

APPLICATIONS

- Power supplies:
 - Uninterruptible power supplies
 - AC/DC switch-mode power supplies
 - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	150				
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Durin Comment (T., 150 °C)	T _C = 25 °C		100			
Continuous Drain Current (T _J = 150 °C)	T _C = 125 °C	- I _D	70			
Pulsed Drain Current (t = 100 μs)	I _{DM}	320	Α			
Avalanche Current	L = 0.1 mH		55			
Single Avalanche Energy ^a	L = 0.1 IIII	E _{AS}	180	mJ		
Maximum Dawar Dissination 3	T _C = 25 °C	В	375 b	W		
Maximum Power Dissipation ^a	T _C = 125 °C	P _D	125 ^b			
Operating Junction and Storage Temperature	T _J , T _{stg}	-55 to +175	°C			

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C ///		
Junction-to-Case (Drain)	R _{thJC}	0.4	°C/W		

Notes

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).

1



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3	-	5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 250	nA	
		V _{DS} = 150 V, V _{GS} = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 150 V, V _{GS} = 0 V, T _J = 125 °C	-	-	100	μA	
		V _{DS} = 150 V, V _{GS} = 0 V, T _J = 175 °C	-	-	2	mA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	90	-	-	Α	
Dunin Course On Otata Basistana 2	_	V _{GS} = 10 V, I _D = 30 A	-	0.0085	-	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, I_D = 30 \text{ A}$	-	0.0095	-		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	-	52	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	3425	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 75 \text{ V}, f = 1 \text{ MHz}$	-	535	-		
Reverse Transfer Capacitance	C _{rss}		-	26	-		
Total Gate Charge ^c	Qg		-	63	95	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$	-	19.5	-		
Gate-Drain Charge ^c	Q _{gd}		-	20.5	-		
Gate Resistance	R_{g}	f = 1 MHz	1.5	3	5	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	15	30		
Rise Time ^c	t _r	$V_{DD} = 75 \text{ V}, R_{L} = 1.25 \Omega$	-	114	220		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D\cong 60$ A, V_{GEN} = 10 V, R_g = 1 Ω	-	28	56	ns	
Fall Time ^c	t _f		-	8	16		
Drain-Source Body Diode Ratings ar	nd Characteri	stics ^b (T _C = 25 °C)					
Pulsed Current (t = 100 μs)	I _{SM}		-	-	240	Α	
Forward Voltage ^a	V _{SD}	I _F = 30 A, V _{GS} = 0 V	-	0.73	1.2	V	
Reverse Recovery Time	t _{rr}		-	110	220	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	$I_F = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	-	10	20	Α	
Reverse Recovery Charge	Q _{rr}		-	0.5	1	μC	

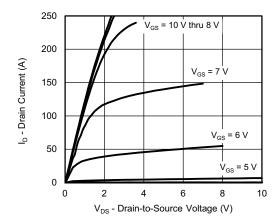
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

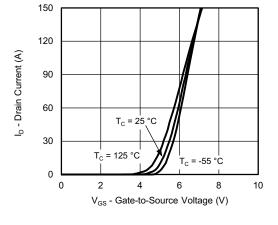
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



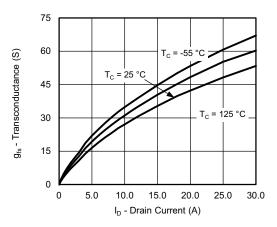
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



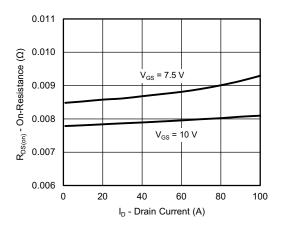
Output Characteristics



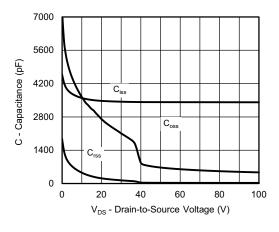
Transfer Characteristics



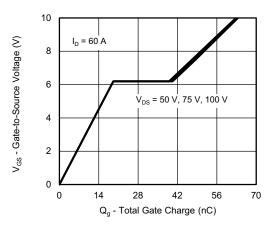
Transconductance



On-Resistance vs. Drain Current



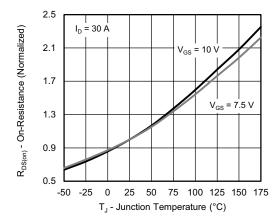
Capacitance



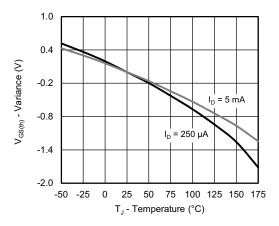
Gate Charge



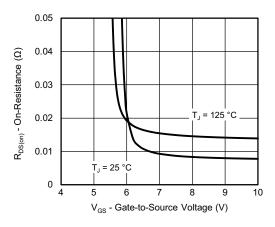
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



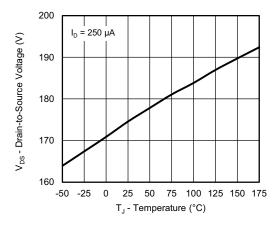
On-Resistance vs. Junction Temperature



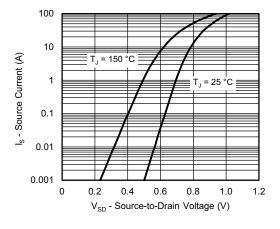
Threshold Voltage



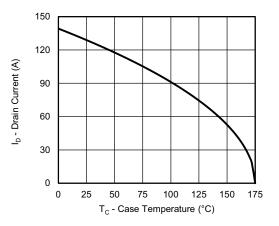
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



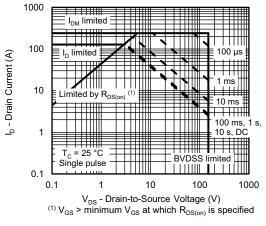
Source Drain Diode Forward Voltage

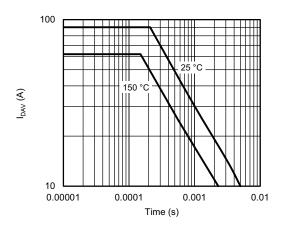


Current De-Rating



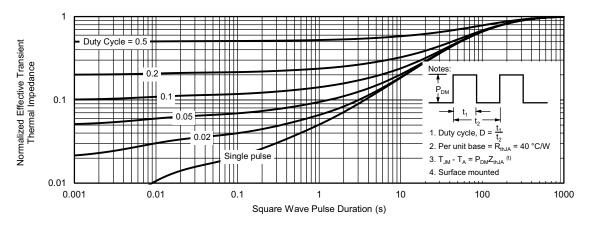
THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)





Safe Operating Area

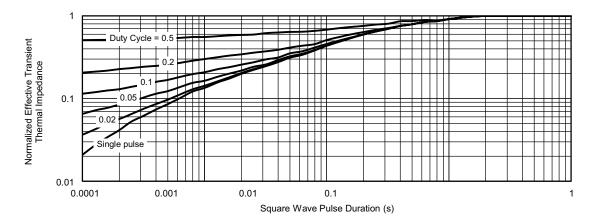
 I_{DAV} vs. Time



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

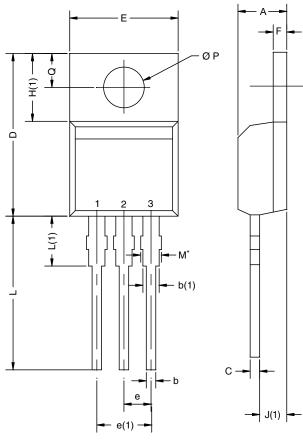
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-220AB



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	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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